

**Assembly Transfer of Select BGA Products and Conversion  
to CSP\_BGA to STATS ChipPAC Korea**

**Qualification Plan Summary for  
CSP\_BGA at STATS ChipPAC Korea**

<b>TEST</b>	<b>SPECIFICATION</b>	<b>SAMPLE SIZE</b>	<b>EXPECTED COMPLETION DATE</b>
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 32	Nov 2020
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	Nov 2020
Temperature Humidity Bias (THB)*	JEDEC <i>JESD22-A101</i>	3 x 32	Nov 2020
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 32	Nov 2020
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC <i>JESD22-A102</i>	3 x 32	Nov 2020

\* Preconditioned per JEDEC/IPC J-STD-020.

# BOM Change Summary

▶ ASDP-BF33 and ADSP-BF533L (19x19\_MM)

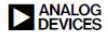
Assembly Site	STATS Singapore - STA (From)	STATS Korea – SK3 (To)
Wire	Au / 1.0 mil	Au / 1.0 mil
Die Attach	Ablestik 2000 conductive	Ablestik 2000B conductive
Mold Compound	Sumitomo G770	Sumitomo G760SYA (Low Alpha)
Ball Size	0.6	0.6
Ball Composition	96.5Sn_3.0Ag_0.5Cu	96.5Sn_3.0Ag_0.5Cu
Plating	100Sn	100Sn

# BOM Change Summary

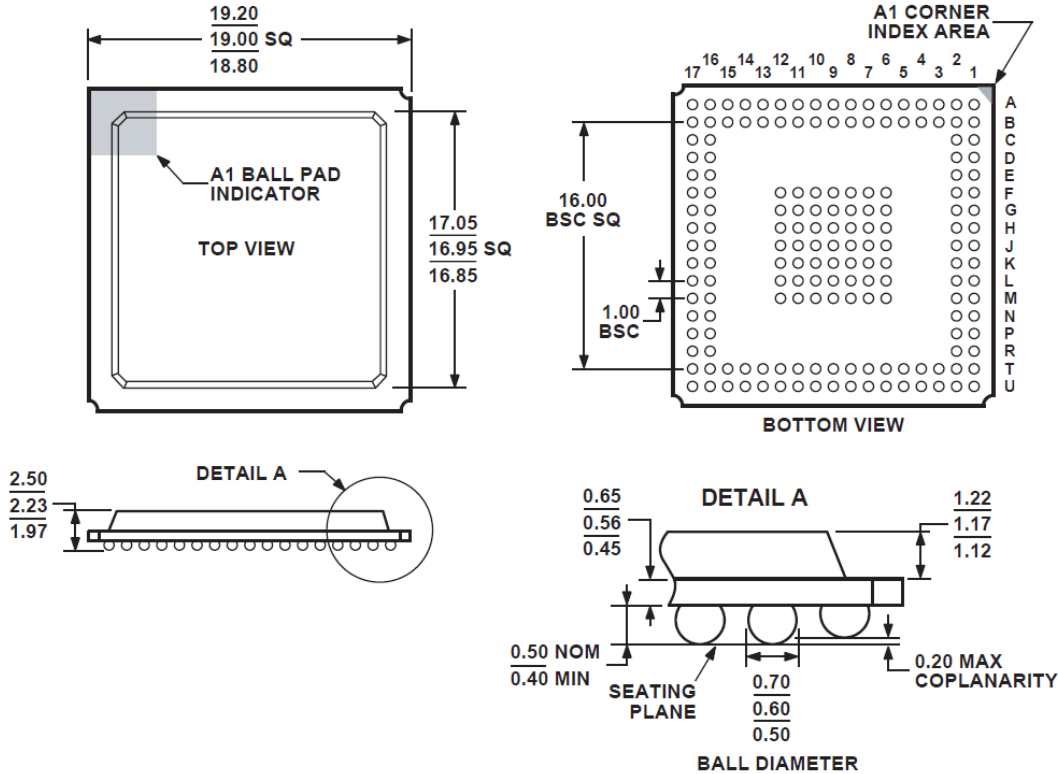
## ▶ ASDP-TS101S (19x19\_MM)

Assembly Site	STATS Singapore - STA (From)	STATS Korea – SK3 (To)
Wire	Au / 1.2 mil	Au / 1.2 mil
Die Attach	Ablestik 2000 conductive	Ablestik 2000B conductive
Mold Compound	Sumitomo G770	Sumitomo G760SYA (Low Alpha)
Ball Size	0.50	0.50
Ball Composition	96.5Sn_3.0Ag_0.5Cu	96.5Sn_3.0Ag_0.5Cu
Plating	100Sn	100Sn

# Package Outline Drawing Summary



**169-Ball Plastic Ball Grid Array [PBGA] (B-169)**  
Dimensions shown in millimeters

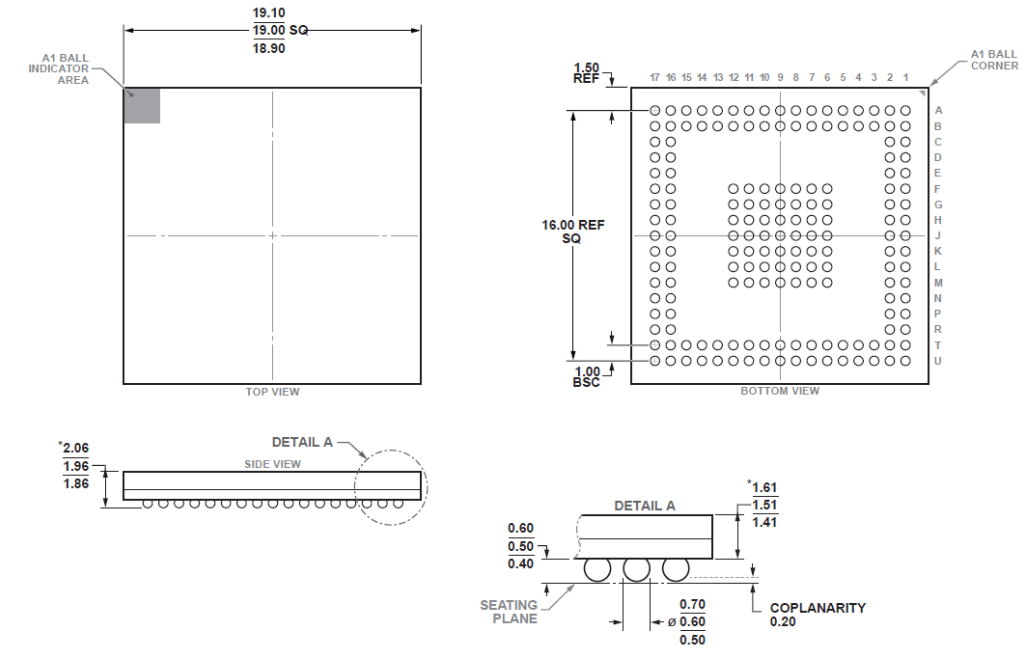


COMPLIANT TO JEDEC STANDARDS MS-034-AAG-2

**PBGA – B-169**  
2.50mm Max Height



**169-Ball Chip Scale Package Ball Grid Array [CSP\_BGA] (BC-169-5)**  
Dimensions shown in millimeters



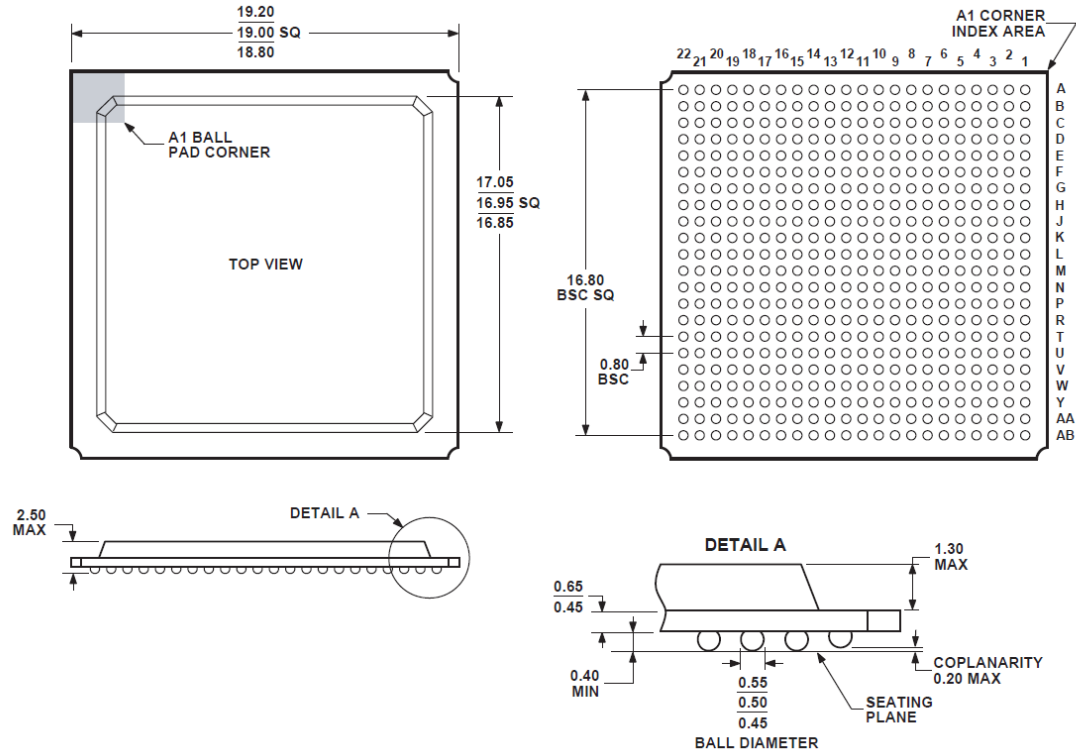
\*COMPLIANT TO JEDEC STANDARDS MO-192-AAG-1  
WITH EXCEPTION TO PACKAGE HEIGHT AND THICKNESS

**CSP\_BGA – BC-169-5**  
2.06mm Max Height

# Package Outline Drawing Summary



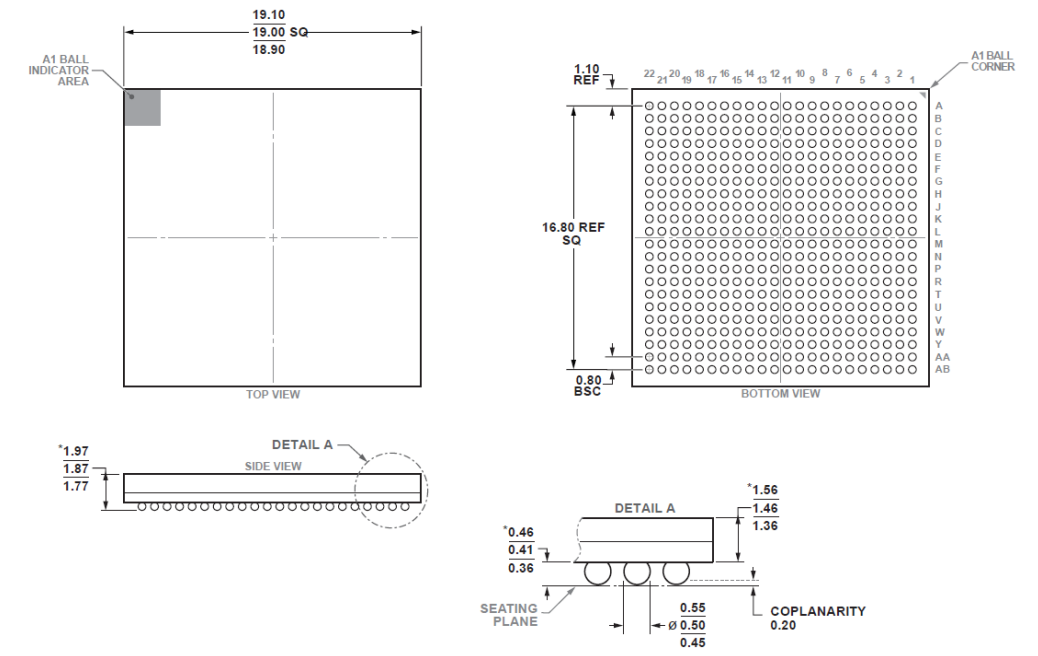
484-Ball Plastic Ball Grid Array [PBGA]  
(B-484)  
Dimensions shown in millimeters



**PBGA – B-484**  
2.50mm Max Height



484-Ball Chip Scale Package Ball Grid Array [CSP\_BGA]  
(BC-484-1)  
Dimensions shown in millimeters



**CSP\_BGA – BC-484-1**  
1.97mm Max Height